

1. Scope :

This specification applies to N/P/N silicon zener double diodes chips,
Device NO. SD-008B0GVA

2. Structure :

- 2-1. Planar type : N/P/N.
- 2-2. Electrodes :
 - Top side : Gold pad.
 - Back side : SnAu Alloy.

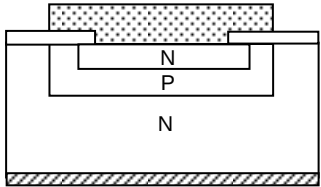
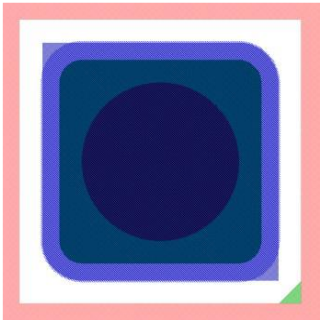
3. Size :

- 3-1. ^{*1} Chip size : 8.5 mils x 8.5 mils (0.215 mm x 0.215 mm).
- 3-2. Chip thickness : 6.0 ± 1.0 mils (0.150 ± 0.025 mm).
- 3-3. ^{*2} Bonding pad : 5.9 mils x 5.9 mils (0.150 mm x 0.150 mm) .
- 3-4. Pattern drawing : Refer to the attached drawing.

^{*1} Including scribing line. The chip size is about (0.190±0.015)²mm² after dicing.
^{*2} The bonding pad dimension is (0.150±0.005)²mm².

4. Electrical characteristics (Ta = 25 °C) _one Zener

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Leakage Current	Idf	V=5V Ee=0mW/cm ²			500	nA
	Idr	V=5V Ee=0mW/cm ²			500	
Zener Voltage	Vz(forward)	Izf=5mA Ee=0mW/cm ²	6		8	V
	Vz(reverse)	Izr=5mA Ee=0mW/cm ²	30			



5. Annotation :

- 5-1. Parallel with one LED
- 5-2. Single pad (one wire bonding applied only)
- 5-3. Double direction Zener diode protection

